NXP USA Inc. - MC908QY1ACDTER Datasheet





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Details

Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	13
Program Memory Size	1.5KB (1.5K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	16-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	16-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc908qy1acdter

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Vector Priority	Vector	Address	Vector
Lowest	IF22- IF16	\$FFD0,1- \$FFDC,D	Not used
Ĩ	IF15	\$FFDE,F	ADC conversion complete vector
	IF14	\$FFE0,1	Keyboard vector
	IF13	—	Not used
	IF12	—	Not used
	IF11	—	Not used
	IF10	—	Not used
	IF9	_	Not used
	IF8	—	Not used
	IF7	_	Not used
	IF6	—	Not used
	IF5	\$FFF2,3	TIM overflow vector
	IF4	\$FFF4,5	TIM channel 1 vector
	IF3	\$FFF6,7	TIM channel 0 vector
	IF2	_	Not used
	IF1	\$FFFA,B	IRQ vector
¥	—	\$FFFC,D	SWI vector
Highest	_	\$FFFE,F	Reset vector

Table 2-1. Vector Addresses

2.5 Random-Access Memory (RAM)

This MCU includes static RAM. The locations in RAM below \$0100 can be accessed using the more efficient direct addressing mode, and any single bit in this area can be accessed with the bit manipulation instructions (BCLR, BSET, BRCLR, and BRSET). Locating the most frequently accessed program variables in this area of RAM is preferred.

The RAM retains data when the MCU is in low-power wait or stop mode. At power-on, the contents of RAM are uninitialized. RAM data is unaffected by any reset provided that the supply voltage does not drop below the minimum value for RAM retention.

For compatibility with older M68HC05 MCUs, the HC08 resets the stack pointer to \$00FF. In the devices that have RAM above \$00FF, it is usually best to reinitialize the stack pointer to the top of the RAM so the direct page RAM can be used for frequently accessed RAM variables and bit-addressable program variables. Include the following 2-instruction sequence in your reset initialization routine (where RamLast is equated to the highest address of the RAM).

LDHX	#RamLast+1	;point one past RAM
TXS		;SP<-(H:X-1)



Memory



Chapter 3 Analog-to-Digital Converter (ADC10) Module

3.1 Introduction

This section describes the 10-bit successive approximation analog-to-digital converter (ADC10).

The ADC10 module shares its pins with general-purpose input/output (I/O) port pins. See Figure 3-1 for port location of these shared pins. The ADC10 on this MCU uses V_{DD} and V_{SS} as its supply and reference pins. This MCU uses BUSCLKX4 as its alternate clock source for the ADC. This MCU does not have a hardware conversion trigger.

3.2 Features

Features of the ADC10 module include:

- Linear successive approximation algorithm with 10-bit resolution
- Output formatted in 10- or 8-bit right-justified format
- Single or continuous conversion (automatic power-down in single conversion mode)
- Configurable sample time and conversion speed (to save power)
- Conversion complete flag and interrupt
- Input clock selectable from up to three sources
- Operation in wait and stop modes for lower noise operation
- Selectable asynchronous hardware conversion trigger

3.3 Functional Description

The ADC10 uses successive approximation to convert the input sample taken from ADVIN to a digital representation. The approximation is taken and then rounded to the nearest 10- or 8-bit value to provide greater accuracy and to provide a more robust mechanism for achieving the ideal code-transition voltage.

Figure 3-2 shows a block diagram of the ADC10

For proper conversion, the voltage on ADVIN must fall between V_{REFH} and V_{REFL} . If ADVIN is equal to or exceeds V_{REFH} , the converter circuit converts the signal to \$3FF for a 10-bit representation or \$FF for a 8-bit representation. If ADVIN is equal to or less than V_{REFL} , the converter circuit converts it to \$000. Input voltages between V_{REFH} and V_{REFL} are straight-line linear conversions.

NOTE

Input voltage must not exceed the analog supply voltages.



Analog-to-Digital Converter (ADC10) Module



Functional Description



Figure 8-2. IRQ Module Block Diagram

8.3.1 MODE = 1

If the MODE bit is set, the IRQ pin is both falling edge sensitive and low level sensitive. With MODE set, both of the following actions must occur to clear the IRQ interrupt request:

- Return of the IRQ pin to a high level. As long as the IRQ pin is low, the IRQ request remains active.
- IRQ vector fetch or software clear. An IRQ vector fetch generates an interrupt acknowledge signal to clear the IRQ latch. Software generates the interrupt acknowledge signal by writing a 1 to ACK in INTSCR. The ACK bit is useful in applications that poll the IRQ pin and require software to clear the IRQ latch. Writing to ACK prior to leaving an interrupt service routine can also prevent spurious interrupts due to noise. Setting ACK does not affect subsequent transitions on the IRQ pin. A falling edge that occurs after writing to ACK latches another interrupt request. If the IRQ mask bit, IMASK, is clear, the CPU loads the program counter with the IRQ vector address.

The IRQ vector fetch or software clear and the return of the IRQ pin to a high level may occur in any order. The interrupt request remains pending as long as the IRQ pin is low. A reset will clear the IRQ latch and the MODE control bit, thereby clearing the interrupt even if the pin stays low.

Use the BIH or BIL instruction to read the logic level on the IRQ pin.

8.3.2 MODE = 0

If the MODE bit is clear, the IRQ pin is falling edge sensitive only. With MODE clear, an IRQ vector fetch or software clear immediately clears the IRQ latch.

The IRQF bit in INTSCR can be read to check for pending interrupts. The IRQF bit is not affected by IMASK, which makes it useful in applications where polling is preferred.

NOTE

When using the level-sensitive interrupt trigger, avoid false IRQ interrupts by masking interrupt requests in the interrupt routine.



Functional Description



Figure 9-2. Keyboard Interrupt Block Diagram

The KBI vector fetch or software clear and the return of all enabled keyboard interrupt pins to a deasserted level may occur in any order.

Reset clears the keyboard interrupt request and the MODEK bit, clearing the interrupt request even if a keyboard interrupt input stays asserted.

9.3.1.2 MODEK = 0

If the MODEK bit is clear, the keyboard interrupt inputs are edge sensitive. The KBIPx bit will determine whether an edge sensitive pin detects rising or falling edges. A KBI vector fetch or software clear immediately clears the KBI latch.

The keyboard flag bit (KEYF) in KBSCR can be read to check for pending interrupts. The KEYF bit is not affected by IMASKK, which makes it useful in applications where polling is preferred.

NOTE

Setting a keyboard interrupt enable bit (KBIEx) forces the corresponding keyboard interrupt pin to be an input, overriding the data direction register. However, the data direction register bit must be a 0 for software to read the pin.



10.4 LVI Interrupts

The LVI module does not generate interrupt requests.

10.5 Low-Power Modes

The STOP and WAIT instructions put the MCU in low power-consumption standby modes.

10.5.1 Wait Mode

If enabled, the LVI module remains active in wait mode. If enabled to generate resets, the LVI module can generate a reset and bring the MCU out of wait mode.

10.5.2 Stop Mode

If the LVIPWRD bit in the configuration register is cleared and the LVISTOP bit in the configuration register is set, the LVI module remains active. If enabled to generate resets, the LVI module can generate a reset and bring the MCU out of stop mode.

The LVI status register (LVISR) contains a status bit that is useful when the LVI is enabled and LVI reset

10.6 Registers

is disabled.



Figure 10-2. LVI Status Register (LVISR)

LVIOUT — LVI Output Bit

This read-only flag becomes set when the V_{DD} voltage falls below the V_{TRIPF} trip voltage and is cleared when V_{DD} voltage rises above V_{TRIPR} . (See Table 10-1).

Table 10-1	. LVIOUT	Bit Indication
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V _{DD}	LVIOUT
$V_{DD} > V_{TRIPR}$	0
$V_{DD} < V_{TRIPF}$	1
$V_{TRIPF} < V_{DD} < V_{TRIPR}$	Previous value



Oscillator (OSC) Module



System Integration Module (SIM)

13.4.2 Active Resets from Internal Sources

The RST pin is initially setup as a general-purpose input after a POR. Setting the RSTEN bit in the CONFIG2 register enables the pin for the reset function. This section assumes the RSTEN bit is set when describing activity on the RST pin.

NOTE For POR and LVI resets, the SIM cycles through 4096 BUSCLKX4 cycles. The internal reset signal then follows the sequence from the falling edge of RST shown in Figure 13-4.

The COP reset is asynchronous to the bus clock.

The active reset feature allows the part to issue a reset to peripherals and other chips within a system built around the MCU.

All internal reset sources actively pull the RST pin low for 32 BUSCLKX4 cycles to allow resetting of external peripherals. The internal reset signal IRST continues to be asserted for an additional 32 cycles (see Figure 13-4). An internal reset can be caused by an illegal address, illegal opcode, COP time out, LVI, or POR (see Figure 13-5).



Figure 13-4. Internal Reset Timing



Figure 13-5. Sources of Internal Reset

	Table	13-2.	Reset	Recovery	Timing
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Reset Recovery Type	Actual Number of Cycles
POR/LVI	4163 (4096 + 64 + 3)
All others	67 (64 + 3)



System Integration Module (SIM)

13.6.3 Reset

All reset sources always have equal and highest priority and cannot be arbitrated.

13.6.4 Break Interrupts

The break module can stop normal program flow at a software programmable break point by asserting its break interrupt output. (See Chapter 15 Development Support.) The SIM puts the CPU into the break state by forcing it to the SWI vector location. Refer to the break interrupt subsection of each module to see how each module is affected by the break state.

13.6.5 Status Flag Protection in Break Mode

The SIM controls whether status flags contained in other modules can be cleared during break mode. The user can select whether flags are protected from being cleared by properly initializing the break clear flag enable bit (BCFE) in the break flag control register (BFCR).

Protecting flags in break mode ensures that set flags will not be cleared while in break mode. This protection allows registers to be freely read and written during break mode without losing status flag information.

Setting the BCFE bit enables the clearing mechanisms. Once cleared in break mode, a flag remains cleared even when break mode is exited. Status flags with a two-step clearing mechanism — for example, a read of one register followed by the read or write of another — are protected, even when the first step is accomplished prior to entering break mode. Upon leaving break mode, execution of the second step will clear the flag as normal.

13.7 Low-Power Modes

Executing the WAIT or STOP instruction puts the MCU in a low power- consumption mode for standby situations. The SIM holds the CPU in a non-clocked state. The operation of each of these modes is described below. Both STOP and WAIT clear the interrupt mask (I) in the condition code register, allowing interrupts to occur.

13.7.1 Wait Mode

In wait mode, the CPU clocks are inactive while the peripheral clocks continue to run. Figure 13-14 shows the timing for wait mode entry.

ADDRESS BUS	WAIT ADDR		DR + 1	SAME	X	SAM	e X
DATA BUS	PREVIOU	S DATA			SAME		SAME
R/W			у				

NOTE: Previous data can be operand data or the WAIT opcode, depending on the last instruction.

Figure 13-14. Wait Mode Entry Timing

A module that is active during wait mode can wake up the CPU with an interrupt if the interrupt is enabled. Stacking for the interrupt begins one cycle after the WAIT instruction during which the interrupt occurred.



Timer Interface Module (TIM)

14.7 I/O Signals

The TIM module can share its pins with the general-purpose I/O pins. See Figure 14-1 for the port pins that are shared.

14.7.1 TIM Channel I/O Pins (TCH1:TCH0)

Each channel I/O pin is programmable independently as an input capture pin or an output compare pin. TCH0 can be configured as buffered output compare or buffered PWM pin.

14.7.2 TIM Clock Pin (TCLK)

TCLK is an external clock input that can be the clock source for the counter instead of the prescaled internal bus clock. Select the TCLK input by writing 1s to the three prescaler select bits, PS[2:0]. 14.8.1 TIM Status and Control Register The minimum TCLK pulse width is specified in the Timer Interface Module Characteristics table in the Electricals section. The maximum TCLK frequency is the least of 4 MHz or bus frequency ÷ 2.

14.8 Registers

The following registers control and monitor operation of the TIM:

- TIM status and control register (TSC)
- TIM control registers (TCNTH:TCNTL)
- TIM counter modulo registers (TMODH:TMODL)
- TIM channel status and control registers (TSC0 and TSC1)
- TIM channel registers (TCH0H:TCH0L and TCH1H:TCH1L)

14.8.1 TIM Status and Control Register

The TIM status and control register (TSC) does the following:

- Enables TIM overflow interrupts
- Flags TIM overflows
- Stops the counter
- Resets the counter
- Prescales the counter clock



Figure 14-4. TIM Status and Control Register (TSC)

TOF — TIM Overflow Flag Bit

This read/write flag is set when the counter reaches the modulo value programmed in the TIM counter modulo registers. Clear TOF by reading the TSC register when TOF is set and then writing a 0 to TOF.



Chapter 15 Development Support

15.1 Introduction

This section describes the break module, the monitor module (MON), and the monitor mode entry methods.

15.2 Break Module (BRK)

The break module can generate a break interrupt that stops normal program flow at a defined address to enter a background program.

Features include:

- Accessible input/output (I/O) registers during the break Interrupt
- Central processor unit (CPU) generated break interrupts
- Software-generated break interrupts
- Computer operating properly (COP) disabling during break interrupts

15.2.1 Functional Description

When the internal address bus matches the value written in the break address registers, the break module issues a breakpoint signal (BKPT) to the system integration module (SIM). The SIM then causes the CPU to load the instruction register with a software interrupt instruction (SWI). The program counter vectors to \$FFFC and \$FFFD (\$FEFC and \$FEFD in monitor mode).

The following events can cause a break interrupt to occur:

- A CPU generated address (the address in the program counter) matches the contents of the break address registers.
- Software writes a 1 to the BRKA bit in the break status and control register.

When a CPU generated address matches the contents of the break address registers, the break interrupt is generated. A return-from-interrupt instruction (RTI) in the break routine ends the break interrupt and returns the microcontroller unit (MCU) to normal operation.

Figure 15-2 shows the structure of the break module.

When the internal address bus matches the value written in the break address registers or when software writes a 1 to the BRKA bit in the break status and control register, the CPU starts a break interrupt by:

- Loading the instruction register with the SWI instruction
- Loading the program counter with \$FFFC and \$FFFD (\$FEFC and \$FEFD in monitor mode)



Development Support

BCFE — Break Clear Flag Enable Bit

This read/write bit enables software to clear status bits by accessing status registers while the MCU is in a break state. To clear status bits during the break state, the BCFE bit must be set.

- 1 = Status bits clearable during break
- 0 = Status bits not clearable during break

15.2.3 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes. If enabled, the break module will remain enabled in wait and stop modes. However, since the internal address bus does not increment in these modes, a break interrupt will never be triggered.

15.3 Monitor Module (MON)

The monitor module allows debugging and programming of the microcontroller unit (MCU) through a single-wire interface with a host computer. Monitor mode entry can be achieved without use of the higher test voltage, V_{TST}, as long as vector addresses \$FFFE and \$FFFF are blank, thus reducing the hardware requirements for in-circuit programming.

Features include:

- Normal user-mode pin functionality
- One pin dedicated to serial communication between MCU and host computer
- Standard non-return-to-zero (NRZ) communication with host computer
- Standard communication baud rate (7200 @ 2-MHz bus frequency)
- Execution of code in random-access memory (RAM) or FLASH
- FLASH memory security feature⁽¹⁾
- FLASH memory programming interface
- Use of external 9.8304 MHz oscillator to generate internal frequency of 2.4576 MHz
- Simple internal oscillator mode of operation (no external clock or high voltage)
- Monitor mode entry without high voltage, V_{TST}, if reset vector is blank (\$FFFE and \$FFFF contain \$FF)
- Normal monitor mode entry if V_{TST} is applied to IRQ

15.3.1 Functional Description

Figure 15-9 shows a simplified diagram of monitor mode entry.

The monitor module receives and executes commands from a host computer. Figure 15-10, Figure 15-11, and Figure 15-12 show example circuits used to enter monitor mode and communicate with a host computer via a standard RS-232 interface.

Simple monitor commands can access any memory address. In monitor mode, the MCU can execute code downloaded into RAM by a host computer while most MCU pins retain normal operating mode functions. All communication between the host computer and the MCU is through the PTA0 pin. A level-shifting and multiplexing interface is required between PTA0 and the host computer. PTA0 is used in a wired-OR configuration and requires a pullup resistor.

^{1.} No security feature is absolutely secure. However, Freescale's strategy is to make reading or copying the FLASH difficult for unauthorized users.

Monitor Module (MON)









A brief description of each monitor mode command is given in Table 15-3 through Table 15-8.



Table 15-3. READ (Read Memory) Command



16.5 5-V DC Electrical Characteristics

Characteristic ⁽¹⁾	Symbol	Min	Typ ⁽²⁾	Max	Unit
Output high voltage $I_{Load} = -2.0$ mA, all I/O pins $I_{Load} = -10.0$ mA, all I/O pins $I_{Load} = -15.0$ mA, PTA0, PTA1, PTA3–PTA5 only	V _{OH}	V _{DD} -0.4 V _{DD} -1.5 V _{DD} -0.8			v
Maximum combined I _{OH} (all I/O pins)	I _{OHT}	—	—	50	mA
Output low voltage $I_{Load} = 1.6$ mA, all I/O pins $I_{Load} = 10.0$ mA, all I/O pins $I_{Load} = 15.0$ mA, PTA0, PTA1, PTA3–PTA5 only	V _{OL}			0.4 1.5 0.8	v
Maximum combined I _{OL} (all I/O pins)	I _{OHL}	—	—	50	mA
Input high voltage PTA0-PTA5, PTB0-PTB7	V _{IH}	0.7 x V _{DD}	_	V _{DD}	V
Input low voltage PTA0–PTA5, PTB0–PTB7	V _{IL}	V _{SS}	_	0.3 x V _{DD}	V
Input hysteresis ⁽³⁾	V _{HYS}	0.06 x V _{DD}	—	—	V
DC injection current, all ports ⁽⁴⁾	I _{INJ}	-2	—	+2	mA
Total dc current injection (sum of all I/O) ⁽⁴⁾	I _{INJTOT}	-25	—	+25	mA
Ports Hi-Z leakage current	IIL	-1	±0.1	+1	μA
Capacitance Ports (as input) ⁽³⁾	C _{IN}	_	_	8	pF
POR rearm voltage	V _{POR}	750	—	—	mV
POR rise time ramp rate ⁽³⁾⁽⁵⁾	R _{POR}	0.035	—	—	V/ms
Monitor mode entry voltage ⁽³⁾	V _{TST}	V _{DD + 2.5}	—	9.1	V
Pullup resistors ⁽⁶⁾ PTA0–PTA5, PTB0–PTB7	R _{PU}	16	26	36	kΩ
Pulldown resistors ⁽⁷⁾ PTA0–PTA5	R _{PD}	16	26	36	kΩ
Low-voltage inhibit reset, trip falling voltage	V _{TRIPF}	3.90	4.20	4.50	V
Low-voltage inhibit reset, trip rising voltage	V _{TRIPR}	4.00	4.30	4.60	V
Low-voltage inhibit reset/recover hysteresis	V _{HYS}	_	100	_	mV

1. V_{DD} = 4.5 to 5.5 Vdc, V_{SS} = 0 Vdc, T_A = T_L to T_H , unless otherwise noted. 2. Typical values reflect average measurements at midpoint of voltage range, 25•C only.

3. Values are based on characterization results, not tested in production.

Values are based on characterization results, not tested in production.
 Guaranteed by design, not tested in production.
 If minimum V_{DD} is not reached before the internal POR reset is released, the LVI will hold the part in reset until minimum V_{DD} is reached.
 R_{PU} is measured at V_{DD} = 5.0 V.
 R_{PD} is measured at V_{DD} = 5.0 V. Pulldown resistors only available when KBIx is enabled with KBIxPOL =1.



Electrical Specifications





Figure 16-1. Typical 5-Volt Output High Voltage versus Output High Current (25°C)







A.2.5 Keyboard Interface Module (KBI) Functionality

The KBI module for the QYxA has the added capability of:

- Triggering a KBI interrupt on the rising or falling edge of an input while the QYx Classic has the capability of triggering on falling edges only.
 - A new register (Keyboard Interrupt Polarity Register) determines the polarity of KBI and the default state of this register configures the QYxA for triggering on falling edges to be compatible with QYx Classic.
 - The QYxA now has pull down resistors for the input pins that are configured for rising edge operation.





Figure A-6. Keyboard Interrupt Polarity Register (KBIPR)

The KBIPR allows the selection of polarity, if any of these bits are set the corresponding interrupt pin will be configured for rising edge and a pulldown resistor will be added to the pin.

A.2.6 On-Chip Routine Enhancements

Enhancements have been made to the on-chip routines that are used for FLASH as EEPROM. Refer to AN2346 for information about using FLASH as EEPROM.

- A new mass erase routine requires a valid FLASH address loaded into the H:X register to perform an erase. This added step helps ensure that the erase routine is not inadvertently used to cause an unwanted erase. Also, on-chip FLASH programming routine ERARNGE variable CTRLBYT requires \$00 for page erase and \$40 for mass erase. The entire control byte must be set for proper operation.
- Separate routines will allow easy access to perform software SCI (Serial Communications Interface). For information on how to use on-chip FLASH programming routines refer to AN2635.
- Finally, there is improved security and robustness. The latest Monitor ROM implements updated security checks to make the program memory more secure.



A.3 Conversion Considerations

Enhancements lead to slight differences in operation from QYx Classic to the QYxA. There are a few points that should be considered in the conversion process.

- The Monitor ROM changed from 2 K to 1 K in size. This has led to the limitation that programming across page boundaries is no longer supported by the on-chip program range routine. Also, in very rare cases, ROM code improvements could cause customers to have to modify a few instructions in their application code. For example, when performing a mass erase, a valid address is required instead of an unspecified address.
- The QYxA contains new modules like the 10-bit ADC and OSC. In rare cases, new modules could cause customers to have to modify a few instructions in their application code. For example, if ADC code was written so that entire registers are configured without respect to reserve bits, then the ADC code will need to be revised to work correctly on the QYxA.
- The Reference Clock for ADC conversions has changed from the bus clock to the system clock (Bus Clock * 4). A change to the divide register may be necessary to set the reference clock to a specified value.

A.4 Code Changes Checklist

Below is a checklist that should be reviewed in the conversion process. This checklist will point out all the issues that should be addressed as your code is ported.

- Does the original software use Auxiliary ROM routines (for example, Getbyte, Putbyte, delnus)? If so, the software will have to be changed to handle new Auxiliary ROM routines, addresses of these routines have changed in QYxA. Code will have to be changed to use the proper addresses.
- 2. Does the software use FLASH as EEPROM?

If so, there are several possible issues for the page erase and mass erase routine. Software will have to be checked to ensure that proper procedure is used and the CTRLBYT is set with a MOV instruction not a BSET. Also, on-chip FLASH programming routines can no longer program across row boundaries

- Does the code use the auto wake up timer and does the application depend on the typical auto wake time out?
 Since the timeout has been improved for QYxA it may be necessary to modify software to compensate for the change in timeout.
- 4. Bits changed in the OSCSC, CONFIG2, and ADC registers? Any code that writes to these registers should be reviewed to ensure that the writes are not affecting the changed bits
- Does the code use external OSC, crystal, or RC?
 If so, since the OSCOPT bits have changed locations code will have to be updated to update these bits in their proper locations.
- 6. Does the code use the ADC?

If so, because on QYxA the ADC clock is driven from 4XBUSCLK instead of BUSCLK changes to the ADC clock divider bits may be needed to maintain proper operation.

